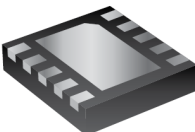


MATERIAL DECLARATION SHEET



Material Number	CDDFN10-3304NA			
Product Line	Semiconductor Products			
Compliance Date	2017/7/20			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.35000	Silicon	7440-21-3	100.00%	4.132%	4.132%
2	Lead frame	Copper Alloy	3.60782	Copper	7440-50-8	95.44%	42.589%	44.622%
			0.09072	Iron	7439-89-6	2.40%	1.071%	
			0.00378	Phosphorous	7723-14-0	0.10%	0.045%	
			0.00567	Zinc	7440-66-6	0.15%	0.067%	
			0.00019	Lead	7439-92-1	0.01%	0.002%	
3	Epoxy	Polymer	0.07182	Silver	7440-22-4	1.90%	0.848%	1.902%
			0.13685	Silver	7440-22-4	85.00%	1.616%	
			0.01369	Resins (Epoxy/Urethane)	Trade Secret	8.50%	0.162%	
4	Wire	Noble metal	0.01047	Additives not to declare	Trade Secret	6.50%	0.124%	1.889%
			0.15998	Gold	7440-57-5	99.99%	1.889%	
5	Mold Compound	Polymer	0.00002	Others	/	0.01%	0.000%	43.441%
			0.18400	Epoxy Resin	Trade Secret	5.00%	2.172%	

MATERIAL DECLARATION SHEET

BOURNS®

			0.18400	Phenol Resin	Trade Secret	5.00%	2.172%	
			2.72320	Silica (Amorphous) A	60676-86-0	74.00%	32.147%	
			0.55200	Silica (Amorphous) B	7631-86-9	15.00%	6.516%	
			0.03680	Carbon Black	1333-86-4	1.00%	0.434%	
6	Plating	Noble metal	0.33966	Tin	7440-31-5	99.90%	4.010%	4.014%
			0.00034	Others not to declare	/	0.10%	0.004%	
		Total weight	8.47101					

This Document was updated on: **2017/7/20**

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.